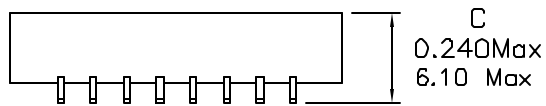
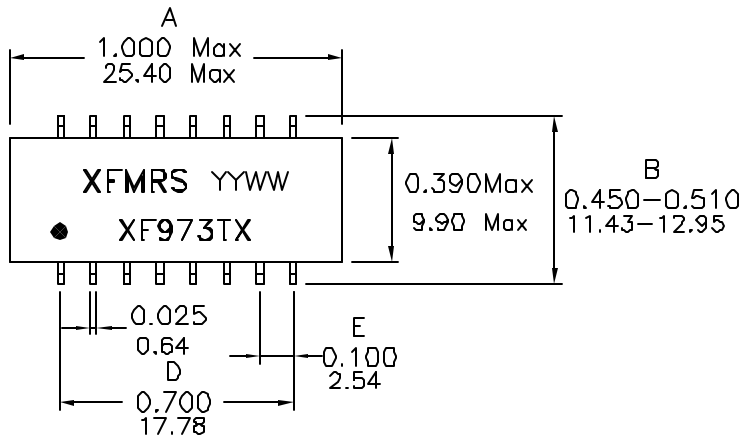
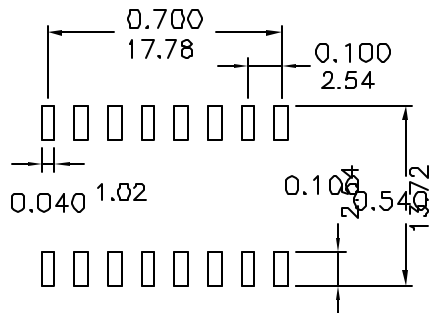
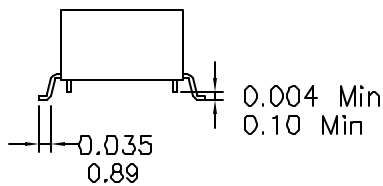


### 1. Mechanical Dimensions:



CO-PLANARITY ± 0.004 Max  
0.10 Max

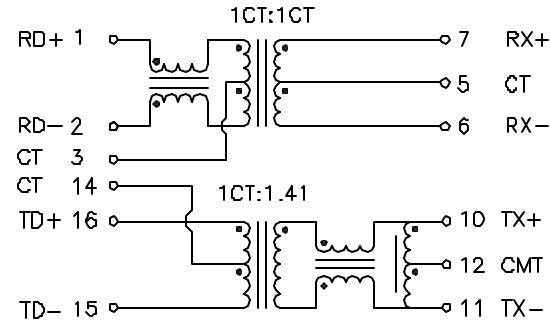


SUGGESTED FOOTPRINT

**Notes:**

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151558
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004" (0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

### 2. Schematic:



### 3. Electrical Specifications:

- Isolation Voltage: 1500 Vrms (Input to Output)
- Turns Ratio: 1-3-2:7-5-6 1CT:1CT±3%
- Turns Ratio: 16-14-15:10-12-11 1CT:1.41±3%
- CHIP SIDE OCL: 350uH Minimum @0.1Vrms 100KHz 8mADC
- Insertion Loss (300KHz-100MHz): -2.0dB Maximum
- Return Loss:
  - 30MHz -18dB Minimum
  - 60MHz -12dB Minimum
  - 80MHz -11dB Minimum
- CROSSTALK:
  - 30MHz -45dB Minimum
  - 60MHz -38dB Minimum
  - 80MHz -34dB Minimum

DOC. REV: B/7

**PROPRIETARY**

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<b>XFMR5 Inc.</b> www.XFMR5.com		Title: HIGH SPEED LAN MAGNETICS	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Inch Dimensions in Inch/mm	P/N: XF973TX		REV. B
	DWN.	Juan Mao	Dec-14-06
	CHK.	YK liao	Dec-14-06
SCALE 2:1 SHT 1 OF 1	APP.	BW	Dec-14-06